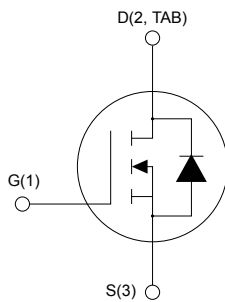
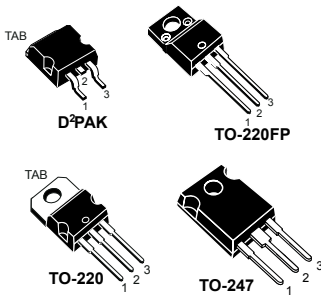




STB34NM60ND, STF34NM60ND STP34NM60ND, STW34NM60ND

Datasheet

N-channel 600 V, 97 mΩ typ., 29 A FDmesh II Power MOSFET in a D²PAK, TO-220FP, TO-220 and TO-247 packages



AM01475v1_noZen



Features

Order code	V _{DS}	R _{DS(on)} max.	I _D
STB34NM60ND	600 V	110 mΩ	29 A
STF34NM60ND			
STP34NM60ND			
STW34NM60ND			

- Fast-recovery body diode
- Low gate charge and input capacitance
- Low on-resistance R_{DS(on)}
- 100% avalanche tested
- High dv/dt ruggedness

Applications

- Switching applications

Description

These FDmesh II Power MOSFET with fast-recovery body diode are produced using MDmesh II technology. Utilizing a new strip-layout vertical structure, these devices feature low on-resistance and superior switching performance. They are ideal for bridge topologies and ZVS phase-shift converters.

Product status links

[STB34NM60ND](#)

[STF34NM60ND](#)

[STP34NM60ND](#)

[STW34NM60ND](#)

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		D ² PAK TO-220 TO-247	TO-220FP	
V _{DS}	Drain-source voltage	600		V
V _{GS}	Gate-source voltage	±25		V
I _D	Drain current (continuous) at T _C = 25 °C	29	29 ⁽¹⁾	A
	Drain current (continuous) at T _C = 100 °C	18	18 ⁽¹⁾	
I _{DM} ⁽²⁾	Drain current (pulsed)	116		A
P _{TOT}	Total power dissipation at T _C = 25 °C	190	40	W
dv/dt ⁽³⁾	Peak diode recovery voltage slope	40		V/ns
V _{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s; T _C = 25 °C)	-	2.5	kV
T _{stg}	Storage temperature range	-55 to 150		°C
T _J	Maximum operating junction temperature	150		

- Limited by maximum junction temperature.
- Pulse width is limited by safe operating area.
- $I_{SD} \leq 29$ A, $di/dt \leq 600$ A/ μ s, $V_{DD} = 480$ V, V_{DS} (peak) < $V_{(BR)DSS}$.

Table 2. Thermal data

Symbol	Parameter	Value				Unit
		D ² PAK	TO-220	TO-247	TO-220FP	
R _{thJC}	Thermal resistance, junction-to-case	0.66			3.1	°C/W
R _{thJA}	Thermal resistance, junction-to-ambient	30 ⁽¹⁾	62.5	50	62.5	°C/W

- When mounted on a standard 1 inch² area of FR-4 PCB with 2-oz copper.

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AR}	Avalanche current, repetitive or not-repetitive (pulse width limited by T _J max.)	7	A
E _{AS}	Single pulse avalanche energy (starting T _J = 25 °C, I _D = I _{AR} , V _{DD} = 50 V)	110	mJ

2 Electrical characteristics

($T_C = 25\text{ °C}$ unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 1\text{ mA}$, $V_{GS} = 0\text{ V}$	600	-	-	V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$, $V_{DS} = 600\text{ V}$	-	-	1	μA
		$V_{GS} = 0\text{ V}$, $V_{DS} = 600\text{ V}$, $T_C = 125\text{ °C}^{(1)}$	-	-	100	
I_{GSS}	Gate body leakage current	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 25\text{ V}$	-	-	± 100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	3	4	5	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}$, $I_D = 14.5\text{ A}$	-	97	110	m Ω

1. Specified by design, not tested in production.

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 50\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0\text{ V}$	-	2785	-	pF
C_{oss}	Output capacitance		-	168	-	pF
C_{riss}	Reverse transfer capacitance		-	5	-	pF
$C_{oss\text{ eq.}}^{(1)}$	Equivalent capacitance time related	$V_{DS} = 0\text{ to }480\text{ V}$, $V_{GS} = 0\text{ V}$	-	438	-	pF
Q_g	Total gate charge	$V_{DD} = 480\text{ V}$, $I_D = 29\text{ A}$, $V_{GS} = 0\text{ to }10\text{ V}$ (see the Figure 18. Test circuit for gate charge behavior)	-	80.4	-	nC
Q_{gs}	Gate-source charge		-	16	-	nC
Q_{gd}	Gate-drain charge		-	41.4	-	nC
R_g	Intrinsic gate resistance	$f = 1\text{ MHz}$, $I_D = 0\text{ A}$	-	2.87	-	Ω

1. $C_{oss\text{ eq.}}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS} .

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 300\text{ V}$, $I_D = 14.5\text{ A}$, $R_G = 4.7\text{ }\Omega$, $V_{GS} = 10\text{ V}$	-	30	-	ns
t_r	Rise time		-	53.4	-	ns
$t_{d(off)}$	Turn-off delay time	(see the Figure 17. Test circuit for resistive load switching times and Figure 22. Switching time waveform)	-	111	-	ns
t_f	Fall time		-	61.8	-	ns

Table 7. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-	-	29	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-	-	116	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 29\text{ A}$, $V_{GS} = 0\text{ V}$	-	-	1.6	V
t_{rr}	Reverse recovery time	$I_{SD} = 29\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$,	-	175	-	ns
Q_{rr}	Reverse recovery charge	$V_{DD} = 60\text{ V}$	-	1.4	-	μC
I_{RRM}	Reverse recovery current	(see the Figure 19. Test circuit for inductive load switching and diode recovery times)	-	16	-	A
t_{rr}	Reverse recovery time	$I_{SD} = 29\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$,	-	255	-	ns
Q_{rr}	Reverse recovery charge	$V_{DD} = 60\text{ V}$, $T_J = 150\text{ }^\circ\text{C}$	-	2.6	-	μC
I_{RRM}	Reverse recovery current	(see the Figure 19. Test circuit for inductive load switching and diode recovery times)	-	20	-	A

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%.

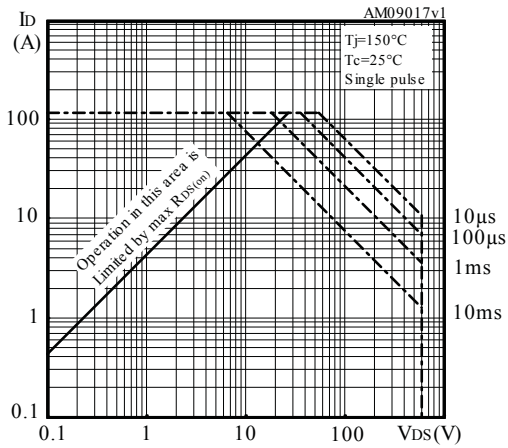
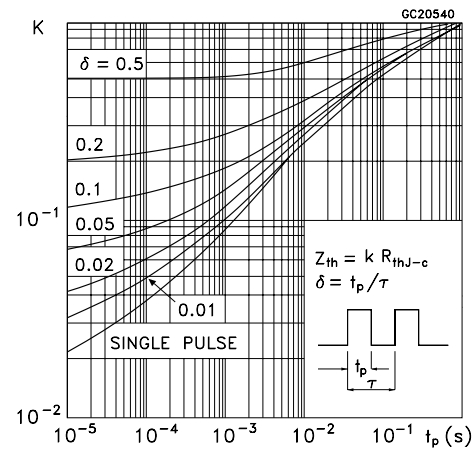
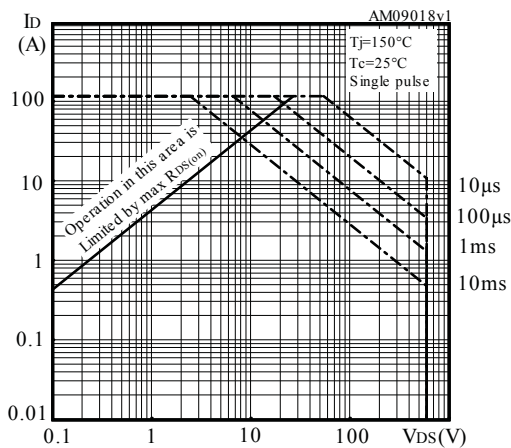
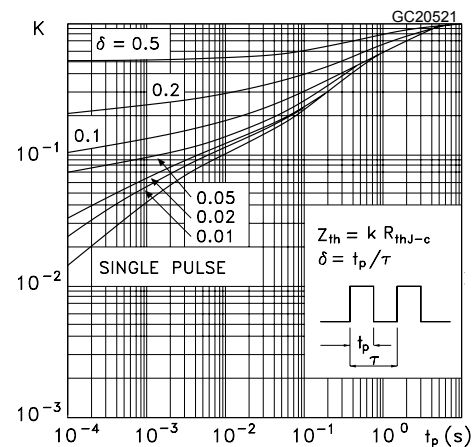
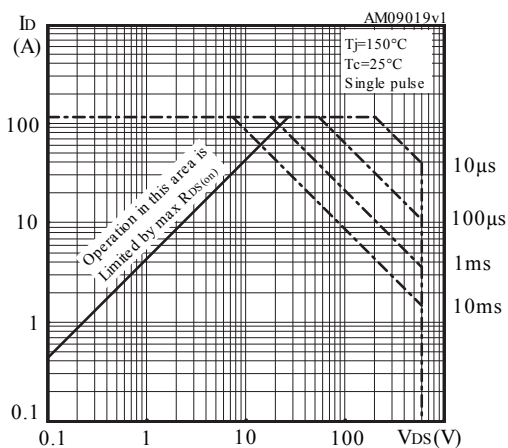
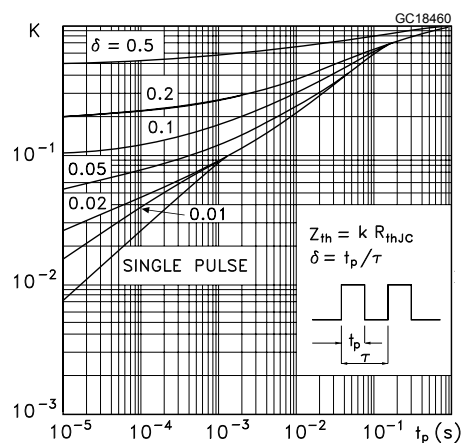
2.1 Electrical characteristics (curves)
Figure 1. Safe operating area for D²PAK and TO-220

Figure 2. Normalized transient thermal impedance for D²PAK and TO-220

Figure 3. Safe operating area for TO-220FP

Figure 4. Normalized transient thermal impedance for TO-220FP

Figure 5. Safe operating area for TO-247

Figure 6. Normalized transient thermal impedance for TO-247


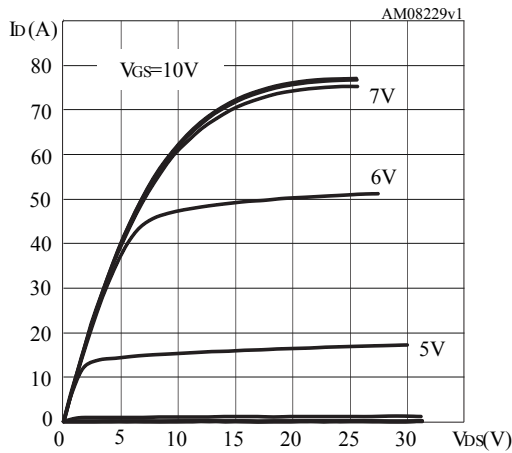
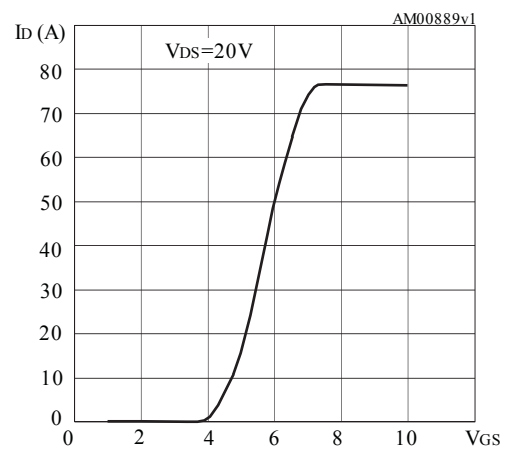
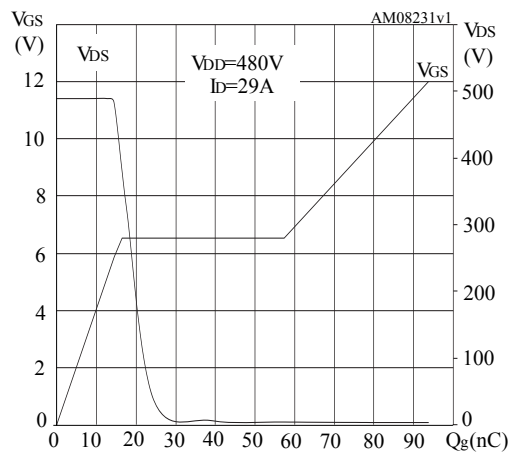
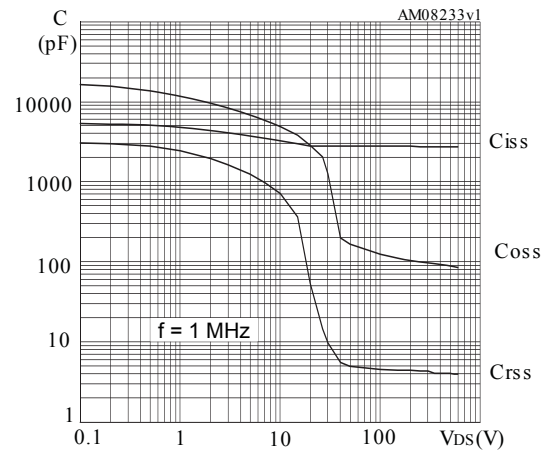
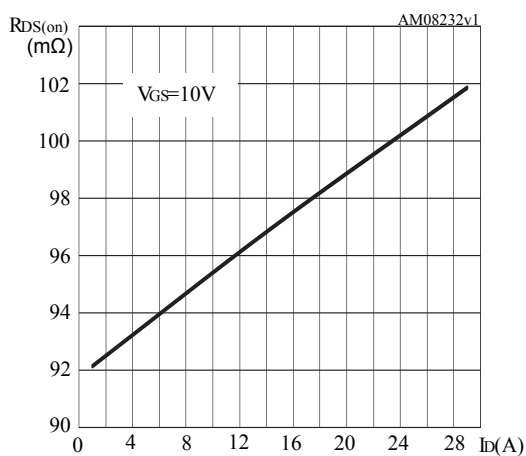
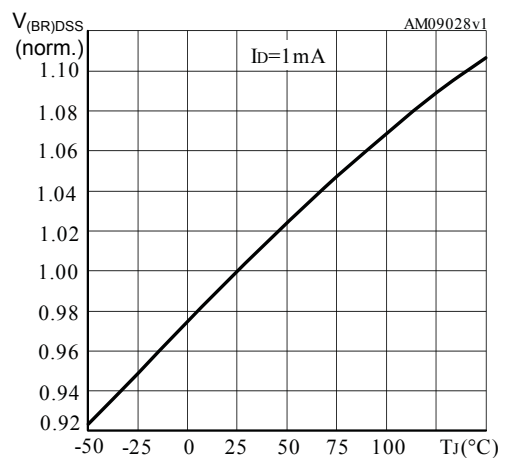
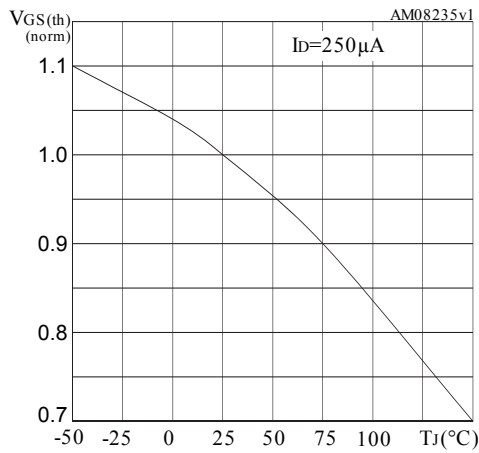
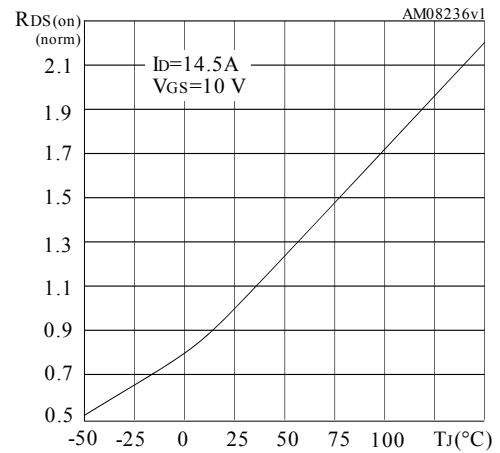
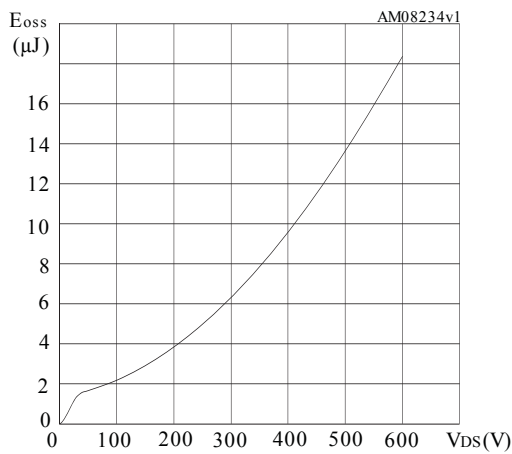
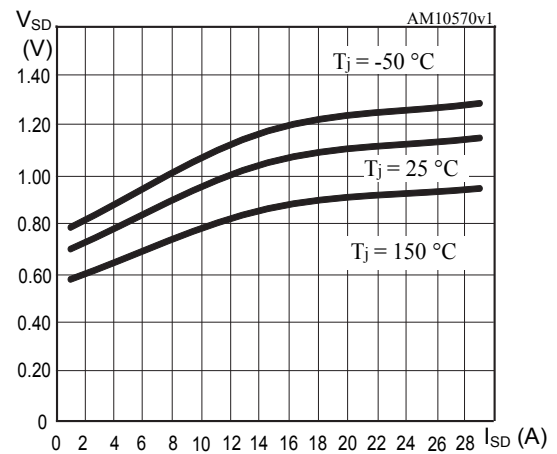
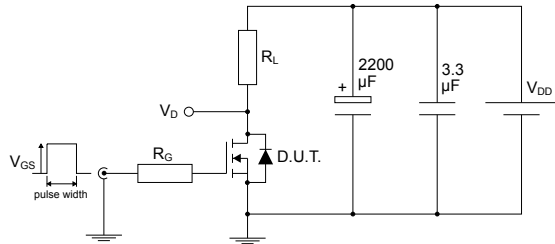
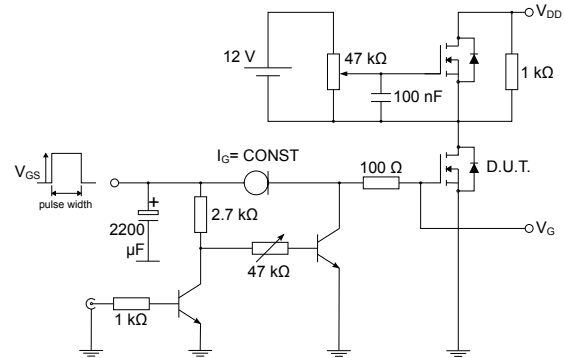
Figure 7. Typical output characteristics

Figure 8. Typical transfer characteristics

Figure 9. Typical gate charge characteristics

Figure 10. Typical capacitance characteristics

Figure 11. Typical drain-source on-resistance

Figure 12. Normalized breakdown voltage vs temperature


Figure 13. Normalized gate threshold vs temperature

Figure 14. Normalized on-resistance vs temperature

Figure 15. Typical output capacitance stored energy

Figure 16. Typical reverse diode forward characteristics


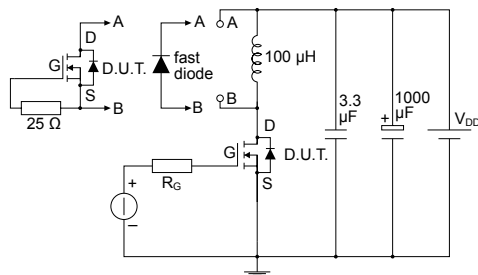
3 Test circuits

Figure 17. Test circuit for resistive load switching times


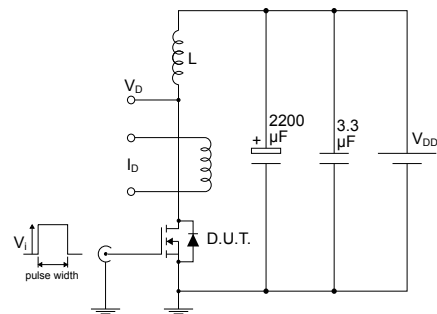
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Figure 18. Test circuit for gate charge behavior


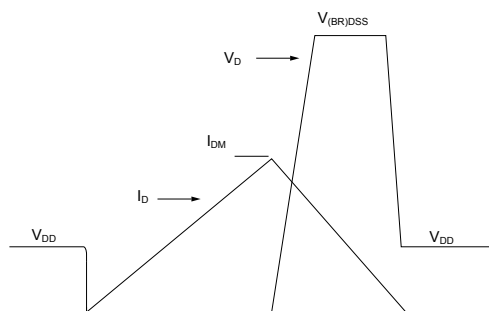
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Figure 19. Test circuit for inductive load switching and diode recovery times


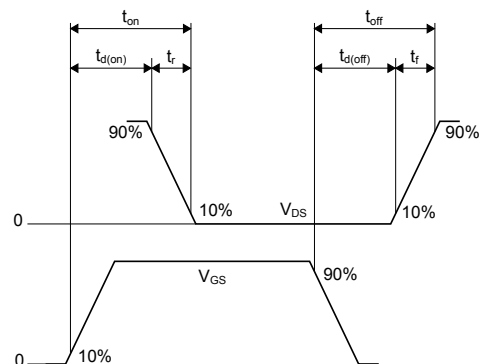
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Figure 20. Unclamped inductive load test circuit


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Figure 21. Unclamped inductive waveform


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Figure 22. Switching time waveform


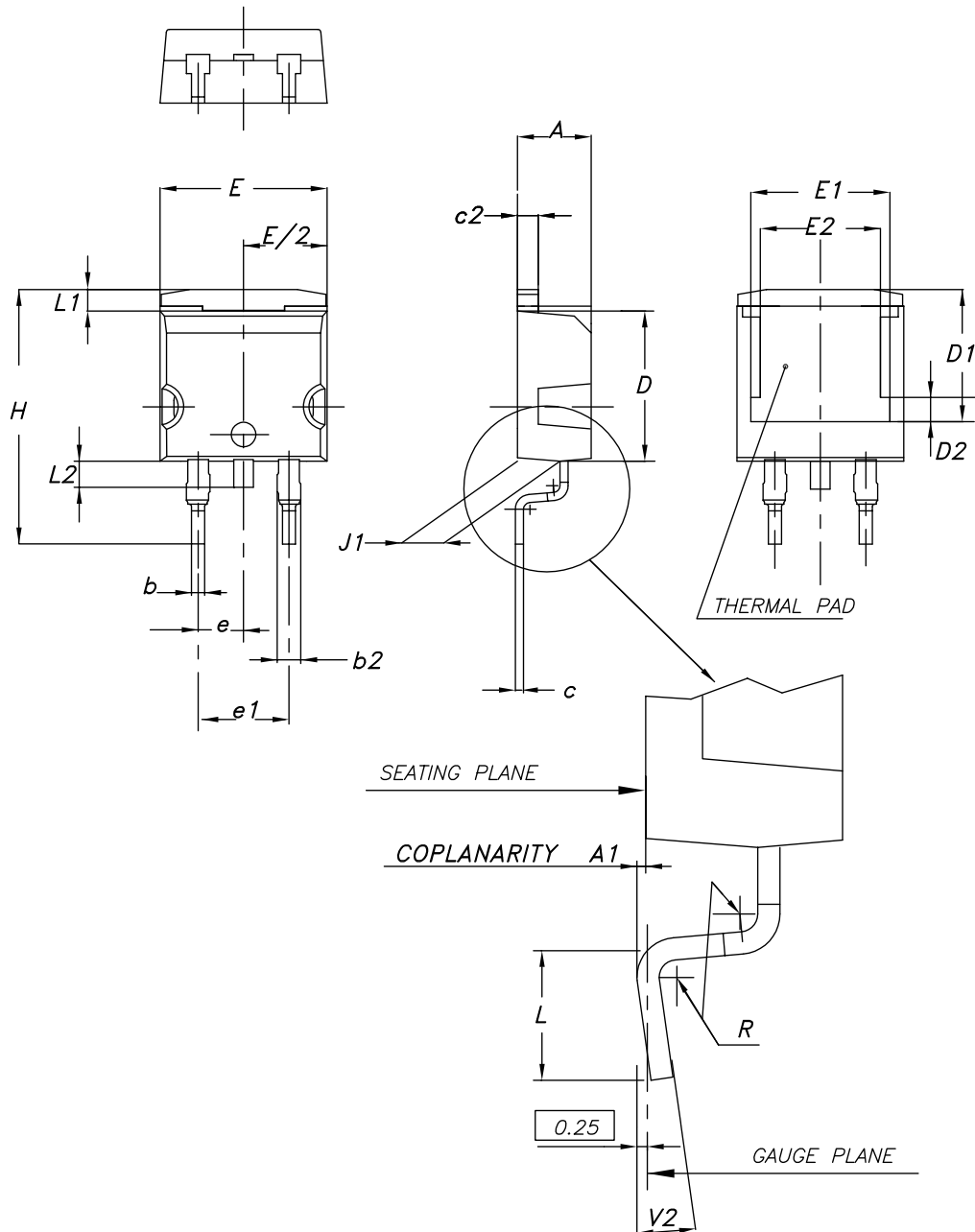
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4 Package information

To meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions, and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 D²PAK (TO-263) type A2 package information

Figure 23. D²PAK (TO-263) type A2 package outline

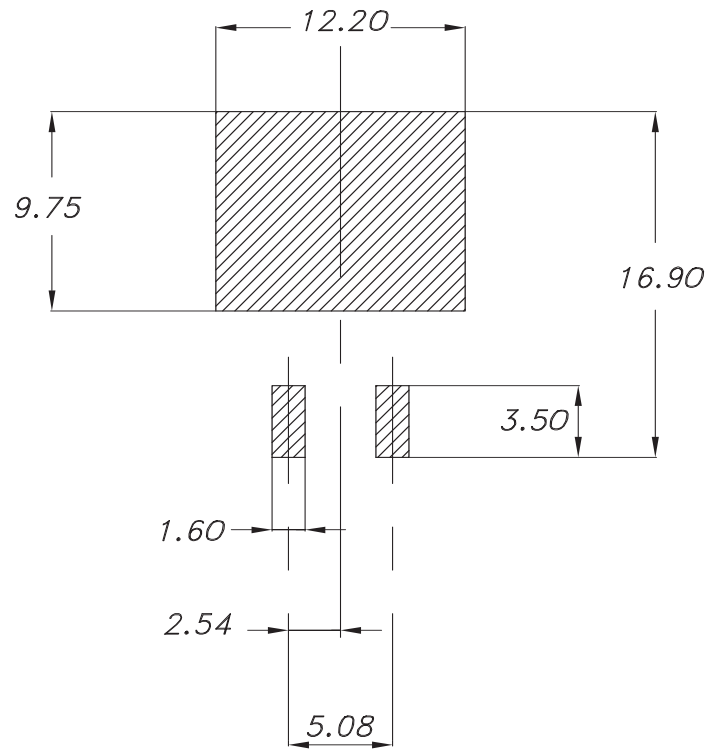


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Table 8. D²PAK (TO-263) type A2 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10.00		10.40
E1	8.70	8.90	9.10
E2	7.30	7.50	7.70
e		2.54	
e1	4.88		5.28
H	15.00		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.40	
V2	0°		8°

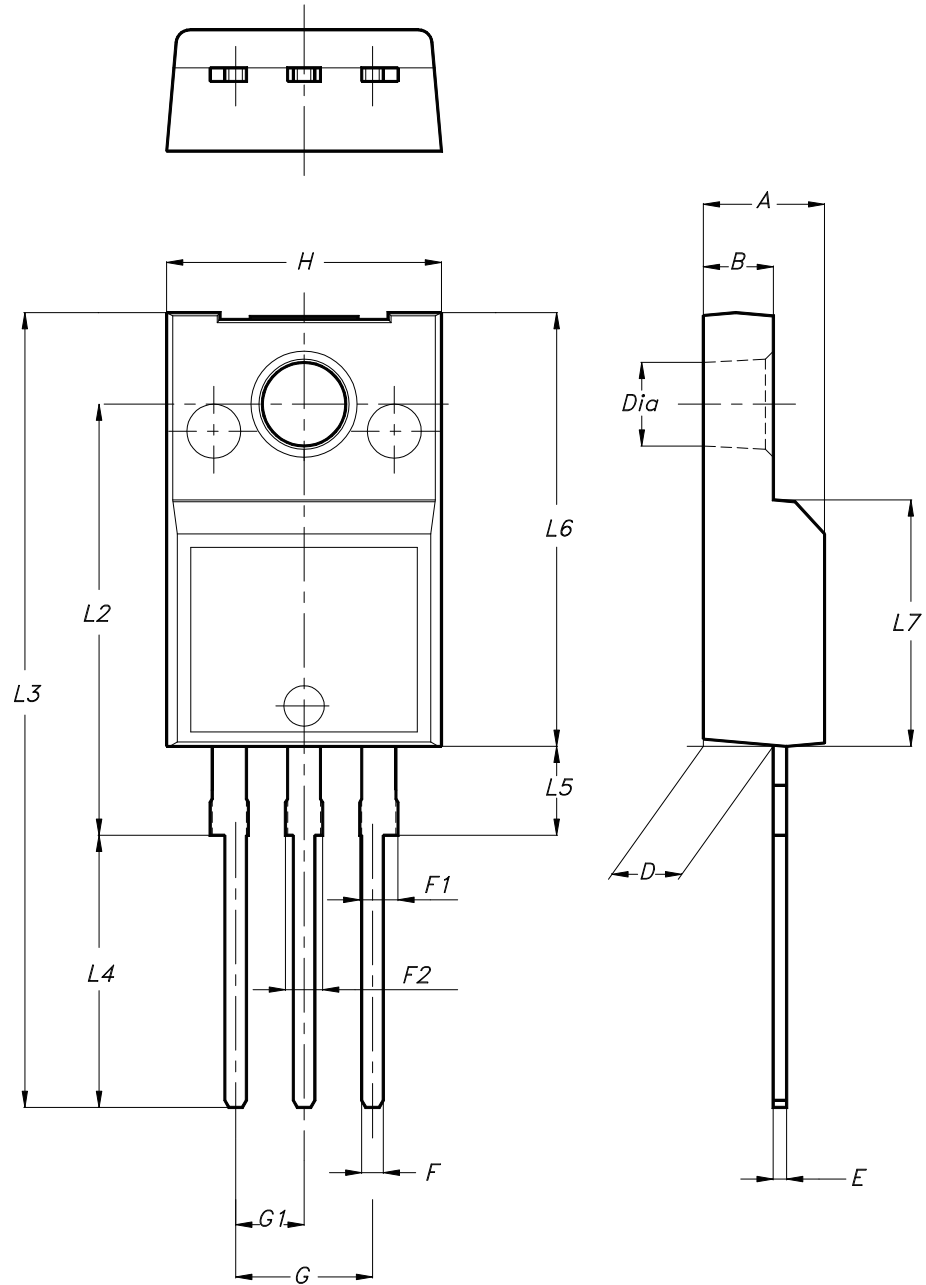
Figure 24. D²PAK (TO-263) recommended footprint (dimensions are in mm)



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4.2 TO-220FP type B package information

Figure 25. TO-220FP type B package outline



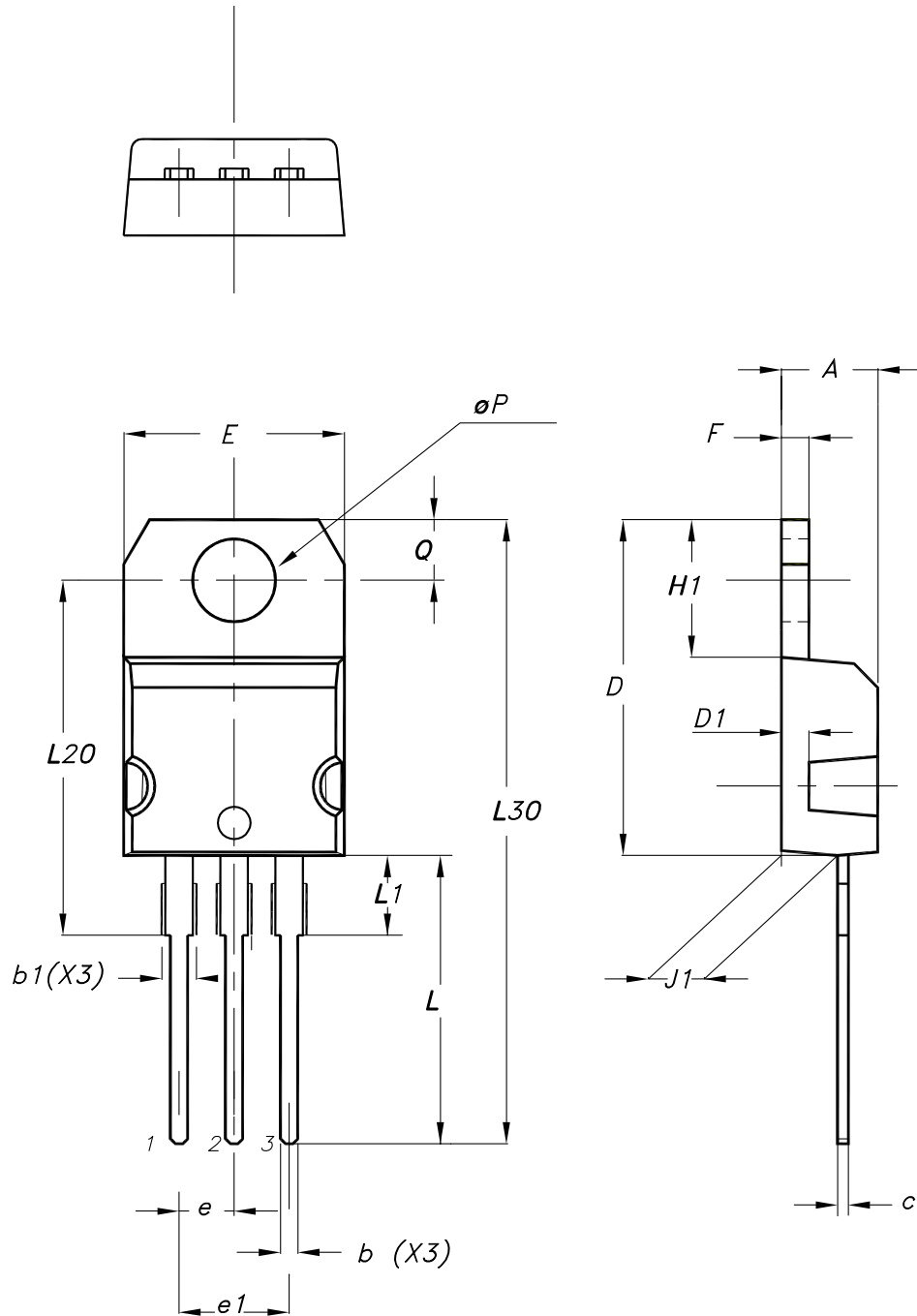
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Table 9. TO-220FP type B package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
B	2.50		2.70
D	2.50		2.75
E	0.45		0.70
F	0.75		1.00
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.20
G1	2.40		2.70
H	10.00		10.40
L2		16.00	
L3	28.60		30.60
L4	9.80		10.60
L5	2.90		3.60
L6	15.90		16.40
L7	9.00		9.30
Dia	3.00		3.20

4.3 TO-220 type A package information

Figure 26. TO-220 type A package outline



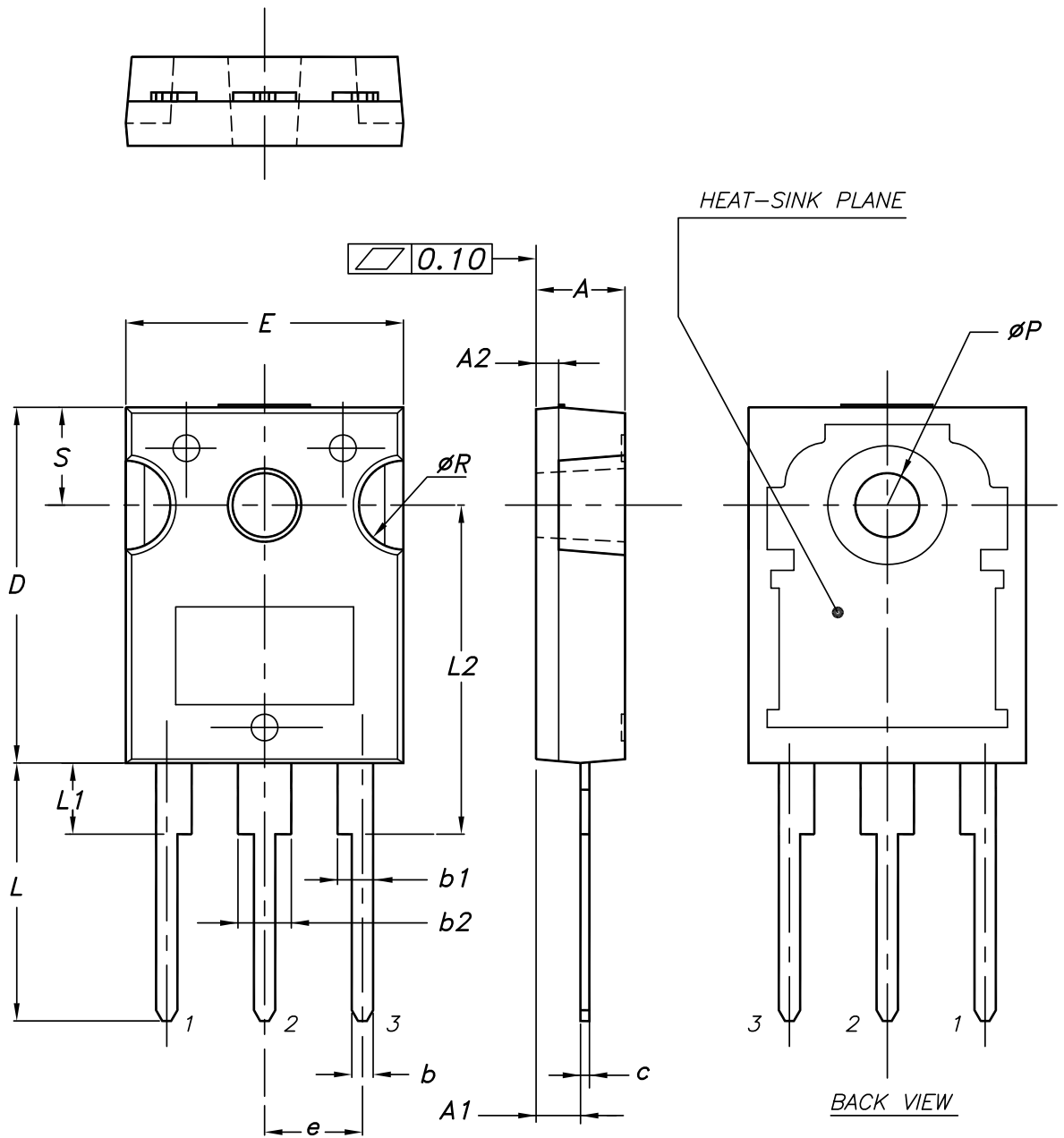
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Table 10. TO-220 type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95
Slug flatness		0.03	0.10

4.4 TO-247 package information

Figure 27. TO-247 package outline



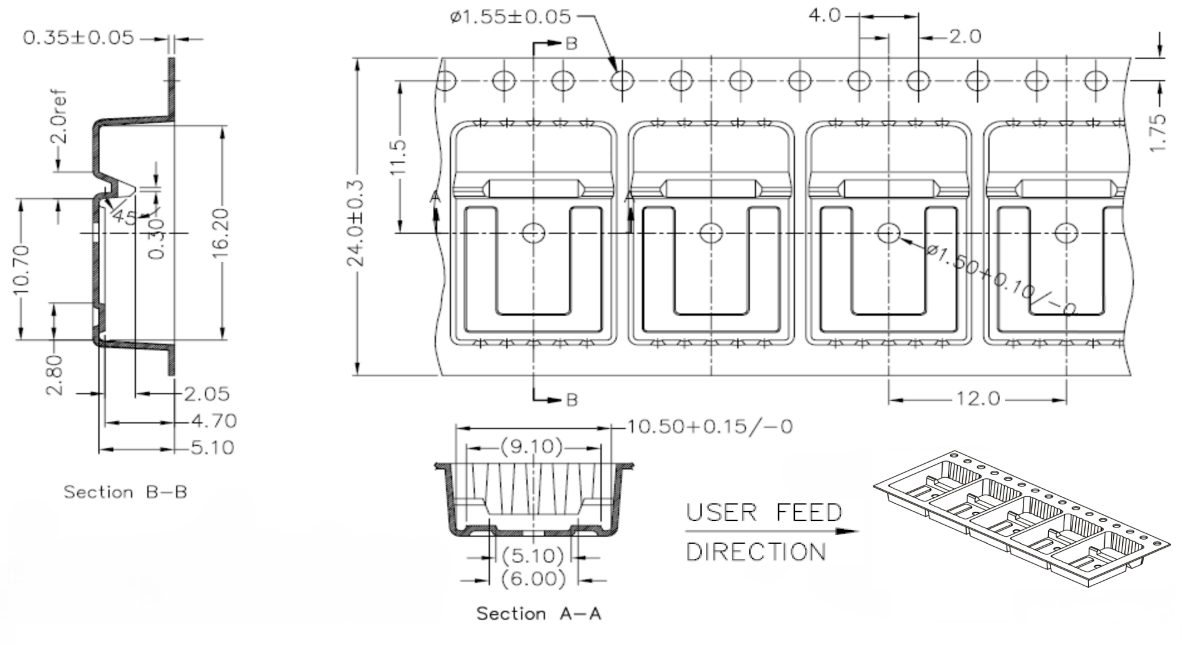
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Table 11. TO-247 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
A2		1.27	
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

4.5 D²PAK packing information

Figure 28. D²PAK tape drawing (dimensions are in mm)



DM01095771_2



5 Ordering information

Table 12. Order codes

Order codes	Marking	Package	Packing
STB34NM60ND	34NM60ND	D ² PAK	Tape and reel
STF34NM60ND		TO-220FP	Tube
STP34NM60ND		TO-220	
STW34NM60ND		TO-247	

Revision history

Table 13. Document revision history

Date	Revision	Changes
04-Nov-2010	1	First release.
18-Apr-2011	2	Corrected E_{AS} value in <i>Table 4: Avalanche characteristics</i> .
14-Sep-2011	3	Added order code in D2PAK and TO-220FP. Updated <i>Table 1: Device summary</i> , <i>Table 2: Absolute maximum ratings</i> and <i>Table 3: Thermal data</i> . Updated <i>Section 4: Package mechanical data</i> . Added <i>Section 5: Packaging mechanical data</i> . Minor text changes.
29-Dec-2011	4	Updated description in cover page.
01-Oct-2012	5	Updated title on the cover page. Updated figures 10, 11, 16 and 17. Updated <i>Section 4: Package mechanical data</i> . Minor text changes.
02-Oct-2013	6	Modified: E_{AS} in <i>Table 4</i> , C_{OSS} eq. typical value in <i>Table 6</i> , <i>Figure 13</i> . Modified: <i>Figure 18, 19, 20 and 21</i> . Minor text changes.
02-Feb-2026	7	Updated <i>Section 4: Package information</i> . Minor text changes.



Contents

1	Electrical ratings	2
2	Electrical characteristics	3
2.1	Electrical characteristics (curves)	5
3	Test circuits	8
4	Package information	9
4.1	D ² PAK (TO-263) type A2 package information	9
4.2	TO-220FP type B package information	12
4.3	TO-220 type A package information	14
4.4	TO-247 package information	16
4.5	D ² PAK packing information	18
5	Ordering information	19
	Revision history	20



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